



Material Content Data Sheet



Sales Product Name		ICE3B0565		Issued		14. November 2014		
MA#		MA001044382						
Package		PG-DIP-8-13		Weight*		556.90 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.262	0.59	0.59	5858	5858
leadframe	inorganic material	phosphorus	7723-14-0	0.054	0.01		96	
	non noble metal	zinc	7440-66-6	0.215	0.04		386	
	non noble metal	iron	7439-89-6	4.297	0.77		7716	
wire	non noble metal	copper	7440-50-8	174.475	31.33	32.15	313294	321492
	noble metal	gold	7440-57-5	0.238	0.04	0.04	428	428
	encapsulation	organic material	carbon black	1333-86-4	1.095	0.20		1966
encapsulation	plastics	epoxy resin	-	35.392	6.36		63551	
	inorganic material	silicondioxide	60676-86-0	328.378	58.96	65.52	589649	655166
leadfinish	non noble metal	tin	7440-31-5	7.496	1.35	1.35	13460	13460
plating	noble metal	silver	7440-22-4	0.796	0.14	0.14	1429	1429
glue	plastics	epoxy resin	-	0.181	0.03		325	
	noble metal	silver	7440-22-4	1.026	0.18	0.21	1842	2167
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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